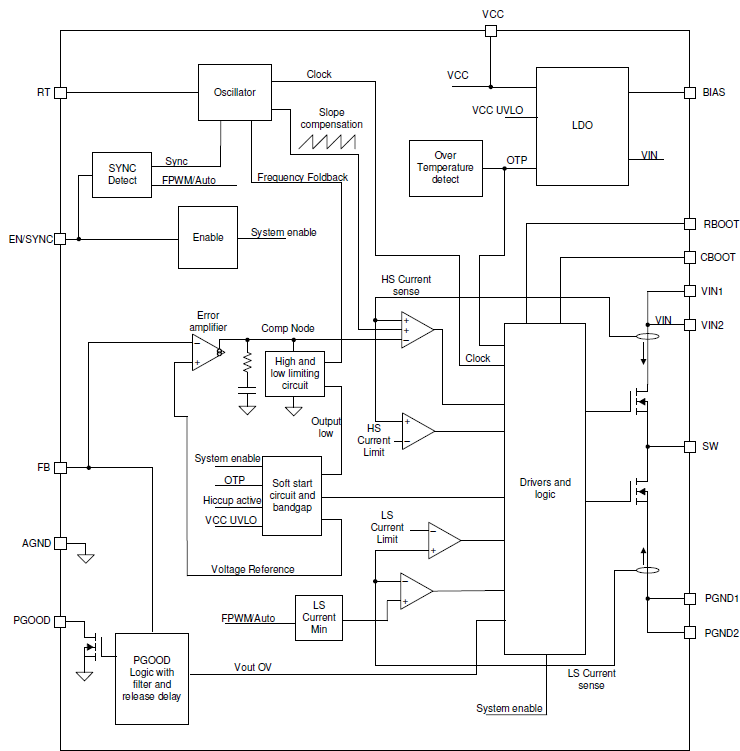


FIT Rate, Failure Mode Distribution LM61440-Q1

Automotive 3-V to 36-V, 4-A, Low-Noise Synchronous Step-Down Converter

Functional Block Diagram



Failure Rate Mission Profile (1)	Per 10 ⁹ Hours (FIT)
Total FIT Rate	16
Die FIT Rate	8
Package FIT Rate	8

Failure Modes	Failure Mode Distribution (%)
SW No output	45%
SW output not in specification – voltage or timing	40%
SW power FET stuck on	5%
PGOOD false trip, fails to trip	5%
Short circuit any two pins	5%

(1) Failure Rate, Mission Profile and Failure Modes Distribution

The failure rate and mission profile information comes from the Reliability data handbook IEC TR 62380 using the reliability modeling for Integrated circuits with automotive motor control mission profiles

Mission Profile: Automotive Motor Control from Table 11

Power dissipation 500mW

Climate type: World-wide Table 8

Package factor lambda 3 Table 17b

Substrate Material: FR4

EOS FIT rate assumed = 0

The failure mode distribution estimation comes from the combination of common failure modes listed in standards such as IEC 61508 and ISO 26262, the ratio of sub-circuit function size and complexity and from best engineering judgment. The failure rates listed reflect random failure events and do not include failures due to misuse or over stress.

LM61440-Q1 are catalog product and not compliant to ISO-26262 standards.

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